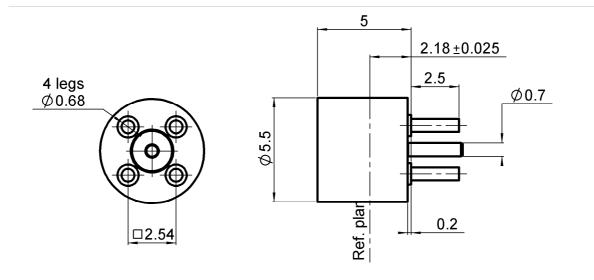
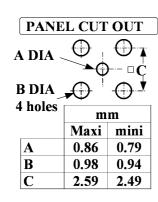
MALE STRAIGHT RECEPTACLE FOR PCB

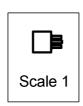
SOLDER LEGS - SMOOTH BORE

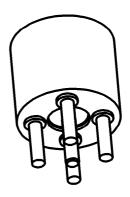
R222.426.700

Series: SMP









All dimensions are in mm.

	COMPONENTS	MATERIALS	PLATINGS (μm)
	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	STAINLESS STEEL BERYLLIUM COPPER PTFE	GOLD 0.5 OVER NICKEL 2 GOLD 1.27 OVER NICKEL 1.27 -
		I	

Issue: 0949 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



MALE STRAIGHT RECEPTACLE FOR PCB

SOLDER LEGS - SMOOTH BORE

R222.426.700

Series: SMP

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-12} \;\; \text{GHz} \end{array}$

VSWR 1.15* + 0,0000 x F(GHz) Maxi

Insertion loss $0.12* \sqrt{F(GHz)} dB Maxi$ RF leakage -(NA - F(GHz)) dB Maxi

 $\begin{array}{cccc} \mbox{Voltage rating} & & \mbox{335} & \mbox{Veff Maxi} \\ \mbox{Dielectric withstanding voltage} & & \mbox{500} & \mbox{Veff mini} \\ \mbox{Insulation resistance} & & \mbox{5000} & \mbox{M}\Omega \mbox{ mini} \\ \end{array}$

ENVIRONMENTAL

Operating temperature -65/+165 ° C Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

*Coaxial Transmission Line Only

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 1000 Cycles mini

Weight **0,7100** g

Issue: 0949 B

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MALE STRAIGHT RECEPTACLE FOR PCB

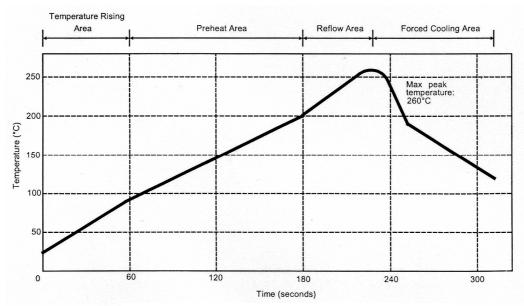
R222.426.700

SOLDER LEGS - SMOOTH BORE

Series: SMP

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
- 2. Place the receptacle on the mounting zone
- Solder 3.
- 4. Clean the printed circuit boards.
- Check the solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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